

## WHAT WE CLAIM IS:

1. A moisture curable adhesive comprising:
  - a) a polymer or copolymer including reactive silicon end groups;
  - b) from about .01 to about 40 percent by weight of a clear filler that will not substantially interfere with the clarity of the adhesive; and
  - c) from about 0.01 to about 10 percent by weight of a dehydrating agent
2. The moisture curable adhesive in claim 1, wherein the adhesive has a viscosity from about 1,000 to about 200,000 centipoise.
3. The moisture curable adhesive in claim 2, wherein the glass transition temperature of the adhesive is less than about -20 °C.
4. The moisture curable adhesive in claim 3, wherein the service temperature range of the adhesive is from about -60°C to about 160 °C.
5. The moisture curable adhesive in claim 4, wherein the clear filler is fumed amorphous silica.
6. The moisture curable adhesive in claim 5, wherein the fumed amorphous silica has a surface area of less than about 250 m<sup>2</sup>/gram.
7. The moisture curable adhesive in claim 1, wherein the filler has a surface area of less than about 250m<sup>2</sup>/gram.
8. The moisture curable adhesive in claim 7, wherein the glass transition temperature of the adhesive is less than about -20°C.

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9. The moisture curable adhesive in claim 8, wherein the service temperature of the adhesive is from about -60°C to about 160 °C.
10. A moisture curable adhesive comprising:
  - a) a polymer or copolymer including reactive silicon end groups;
  - b) from about 33 to about 85 percent by weight of a filler; and
  - c) from about 0.01 to about 10 percent by weight of a dehydrating agent.
11. The moisture curable adhesive in claim 10, wherein the adhesive has a viscosity of from about 1,000 to about 200,000 centipoise.
12. The moisture curable adhesive in claim 11, wherein the glass transition temperature of the adhesive is less than about 20 °C.
13. The moisture curable adhesive in claim 12, wherein the adhesive further comprises from about 0.01 to about 2.5 percent by weight of a catalyst.
14. A method of joining at least two adherends comprising the steps of:
  - a) applying a layer of from about 1.1 mm to about 7 mm of moisture curable adhesive comprising a polymer or copolymer including reactive silicon end groups to at least one adherend of two adherends;
  - b) maintaining the two adherends in non-contact with each other until the adhesive begins to develop a sufficient tack to hold the at least two adherends together; and

- c) first contacting and then forming a bond between the two adherends with the adhesive.
15. The method of joining the at least two adherends in claim 14, wherein the two adherends are maintained in non-contact with each other for less than about 20 minutes.
16. The method of joining the at least two adherends in claim 15, further comprising the step of repositioning the two adherends with respect to each other greater than about 5 minutes after they are first contacted.
17. The method of joining the at least two adherends in claim 16, wherein the two adherends can be repositioned with respect to each other greater than about 20 minutes after they are first contacted.
18. The method of joining the at least two adherends in claim 17, wherein the bond between the two adherends is 90 % cured in less than 8 hours.
19. A method of joining at least two adherends comprising the steps of:
- a) applying a layer of moisture curable adhesive comprising a polymer or copolymer including reactive silicon end groups to at least one adherend of two adherends;
  - b) maintaining the two adherends in non-contact with each other for less than about 20 minutes until the adhesive begins to cure; and
  - c) first contacting then forming a bond between the two adherends with the adhesive

wherein the two adherends can be repositioned after contacting and the adhesive reaches an initial cure in less than thirty minutes.

20. The method of joining the at least two adherends in claim 19, wherein the two adherends are maintained in non-contact with each other for less than about 20 minutes.
21. The method of joining the at least two adherends in claim 20, further comprising the step of repositioning the two adherends with respect to each other more than 5 minutes after they are first contacted.
22. The method of joining the at least two adherends in claim 21, wherein the two adherends can be repositioned with respect to each other more than 20 minutes after they are first contacted.
23. The method of joining the at least two adherends in claim 22, wherein the bond between the two adherends is 90 % cured in less than 8 hours.

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